

Title (en)

ELECTRONIC PACKAGE WITH ENHANCED PAD DESIGN

Title (de)

ELEKTRONISCHE PACKUNG MIT VERBESSERTEM MUSTER FÜR DIE ANSCHLUSSFLÄCHE

Title (fr)

MODULE ELECTRONIQUE A CONCEPTION AVANCEE DE PLAGES DE CONNEXION

Publication

EP 0853817 A1 19980722 (EN)

Application

EP 96932706 A 19961003

Priority

- GB 9602420 W 19961003
- IT 9500161 W 19951004

Abstract (en)

[origin: WO9713275A1] An electronic package (400), particularly a BGA, including a circuitized substrate (120) and one or more active devices (110) attached thereon by means of corresponding conductive pads provided on a surface of the substrate (120); each conductive pad is splitted in a plurality of parts (212-218) not in contact. Such parts (212-218) may be separated by a wireable area of the substrate (120), thereby providing one or more wiring channels. In addition, the same parts (212-218) may be connected in interfacing couples at different electrical potentials (ground and power) and decoupled to each other by means of capacitors (410); the connections to the ground and power are achieved by metallized holes provided through the substrate (120).

IPC 1-7

H01L 23/498; **H01L 21/60**; **H01L 23/31**; **H01L 23/64**

IPC 8 full level

H01L 23/12 (2006.01); **H01L 23/31** (2006.01); **H01L 23/498** (2006.01); **H01L 23/64** (2006.01)

CPC (source: EP KR)

H01L 23/3128 (2013.01 - EP); **H01L 23/498** (2013.01 - KR); **H01L 23/49822** (2013.01 - EP); **H01L 23/642** (2013.01 - EP); **H01L 24/32** (2013.01 - EP); **H01L 24/48** (2013.01 - EP); **H01L 24/73** (2013.01 - EP); **H01L 2224/29111** (2013.01 - EP); **H01L 2224/32057** (2013.01 - EP); **H01L 2224/32225** (2013.01 - EP); **H01L 2224/48091** (2013.01 - EP); **H01L 2224/48227** (2013.01 - EP); **H01L 2224/73265** (2013.01 - EP); **H01L 2224/83385** (2013.01 - EP); **H01L 2924/0001** (2013.01 - EP); **H01L 2924/00014** (2013.01 - EP); **H01L 2924/01005** (2013.01 - EP); **H01L 2924/01006** (2013.01 - EP); **H01L 2924/01013** (2013.01 - EP); **H01L 2924/01029** (2013.01 - EP); **H01L 2924/01032** (2013.01 - EP); **H01L 2924/01033** (2013.01 - EP); **H01L 2924/01039** (2013.01 - EP); **H01L 2924/01047** (2013.01 - EP); **H01L 2924/0105** (2013.01 - EP); **H01L 2924/01052** (2013.01 - EP); **H01L 2924/01061** (2013.01 - EP); **H01L 2924/01074** (2013.01 - EP); **H01L 2924/01077** (2013.01 - EP); **H01L 2924/01079** (2013.01 - EP); **H01L 2924/01082** (2013.01 - EP); **H01L 2924/0132** (2013.01 - EP); **H01L 2924/01322** (2013.01 - EP); **H01L 2924/09701** (2013.01 - EP); **H01L 2924/1517** (2013.01 - EP); **H01L 2924/15311** (2013.01 - EP); **H01L 2924/16152** (2013.01 - EP); **H01L 2924/181** (2013.01 - EP); **H01L 2924/19041** (2013.01 - EP); **H01L 2924/19105** (2013.01 - EP)

Citation (search report)

See references of WO 9713275A1

Designated contracting state (EPC)

DE GB IE

DOCDB simple family (publication)

WO 9713275 A1 19970410; EP 0853817 A1 19980722; JP 3093278 B2 20001003; JP H11508409 A 19990721; KR 100276858 B1 20010115; KR 19990064001 A 19990726; TW 299564 B 19970301

DOCDB simple family (application)

GB 9602420 W 19961003; EP 96932706 A 19961003; JP 51407297 A 19961003; KR 19980702478 A 19980403; TW 85105592 A 19960511